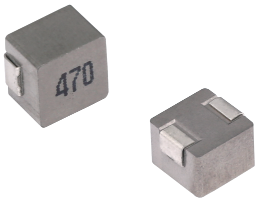
MCMB-0650-101MT01
High Current Molded Power Inductors

FEATURES



- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- Frequency range up to 3MHz
- Operate temperature range .... －40℃～＋125℃(Including self temp. rise)
- RoHS compliant

APPLICATIONS

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Smart phone POL modules
- SSD modules
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

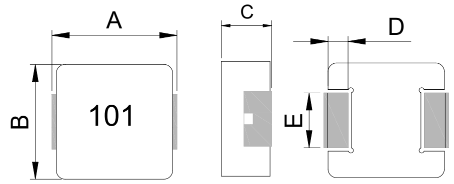
Explanation of Part Number

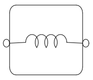
MCMB -0650 -101 M T 01

1 2 3 4 5 6

- ♦ 1:Product Series:Metal Alloy Molding Power Inductor
- ♦ 2:Dimensions:
- ♦ 3: Initial inductance value: 101 = 100uH
- ♦ 4:Tolerance of Inductance:M:±20%
- ♦ 5:Packing:Tape Carrier Package
- ♦ 6: Internal code

Dimensions

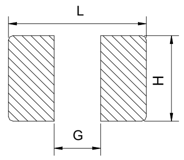




A	B	C	D	E
7.3±0.3	6.6±0.3	4.8±0.2	1.6±0.3	3.0±0.2

Unit:mm

Recommend PC Board Pattern



L	G	H
8.0	3.5	3.4

Note: 1.PCB layout is referred to standard IPC-7351B
2. The above PCB layout reference only.
3. Recommend solder paste thickness at 0.15mm and above.

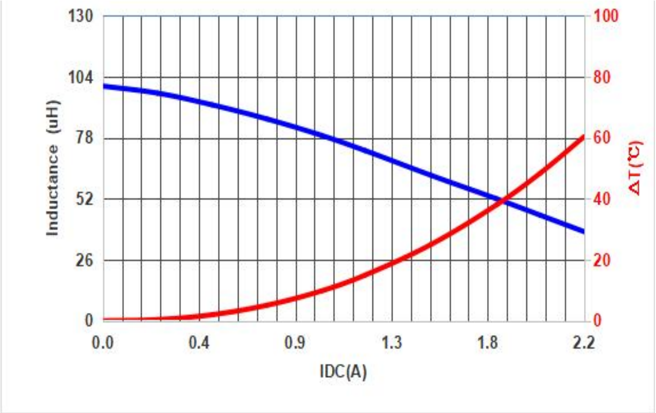
Electrical Properties:

Part Number	Inductance (uH) ±20% @ 0 A DC	Irms (A)		Isat (A)		DCR (mΩ)	
		Typ	Max	Typ	Max	Typ	Max
MCMB-0650-101MT01	100.0	1.8	1.4	1.2	1.0	432	520

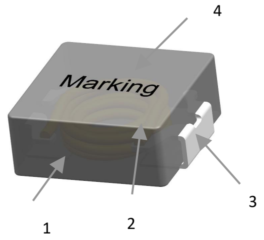
Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of Irms and Isat.

TYPICAL ELECTRICAL CHARACTERISTICS



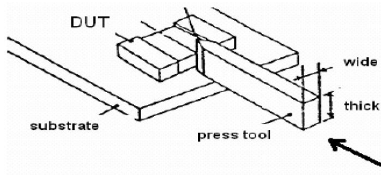
Material List



NO	Items	Materials
1	Core	Alloy Powder .
2	Wire	Polyester Wire or equivalent.
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Ink	Halogen-free ketone

Reliability and Test Condition

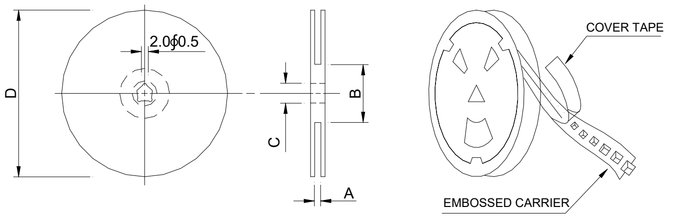
Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	N/A
Storage temperature	1. -10~+40℃,50~60%RH (Product with taping) 2. -40~+125℃(on board)	N/A
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	Agilent4284A,E4991A,KEYSIGHTE4980A/AL,chroma3302,3205
DCR		Agilent 4339B,chrom16502
Saturation Current (Isat)	Approximately △30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Inductance：within±10% of initial value RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times. times.(IPC/JEDECJ-STD-020E Classification Reflow Profiles) Temperature： 125±2℃(Inductor，ambient + temp rise) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs.
Load Humidity		Preconditioning: Run through IR reflow for 3 times times.(IPC/JEDECJ-STD-020E Classification Reflow Profiles) Humidity：85±2％R.H, Temperature：85℃±2℃ Duration：1000hrs Min.(No load current) Measured at room temperature after placing for 24±2 hrs.
Moisture Resistance		Preconditioning: Run through IR reflow for 3 times. times.(IPC/JEDECJ-STD-020E Classification Reflow Profiles) 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25 ℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDECJ-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：125±2℃ ≦20S Step3：125±2℃ 30±5min Step4：-40±2℃ ≦20S Number of cycles： 500 Measured at room fempraturc after placing for 24±2 hrs.
Vibration		Preconditioning: Run through IR reflow for 3 times. times.(IPC/JEDECJ-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz～2KHz～10Hz for 20 minutes Equipment： Vibration checker Total Amplitude: 10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。

<table>
<tr><th>Item</th><th>Performance</th><th>Test Condition</th></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Inductance：within±10% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td><table>
<tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
3 shocks in each direction along 3 perpendicular axes(18 shocks).</td></tr>
<tr><td>Solderability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Solder: Sn96.5% Ag3% Cu0.5%
Method B, 4 hrs @ 155°C dry heat
Temperature: 245±5℃。
Dip time: 5+0/-0.5s。</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Inductance：within±10% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Depth: completely cover the termination
<table>
<tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr>
<tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr>
</table></td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through IR reflow for 3 times.
(IPC/JEDEC J-STD-020E Classification Reflow Profiles
With the component mounted on a PCB with the device to be tested,applyaforce(>0805inch(2012mm):1kg,<=0805inch(2012 mm):0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

</td></tr>
</table>

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

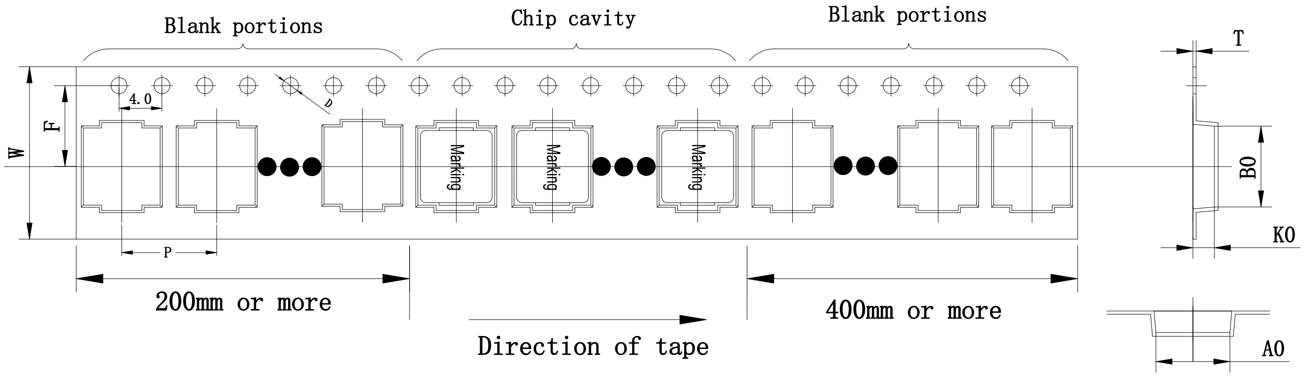
Packaging Information

(1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x16mm	16.4+2/-0	100±2	13+0.5/-0.2	330

(2) Tape Dimension



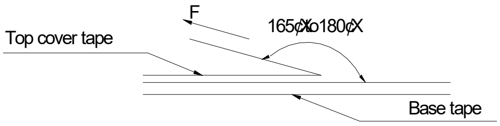
Bo	Ao	Ko	P	W	F	t	D
7.7±0.1	7.0±0.1	5.3±0.1	12.0±0.1	16±0.3	7.5±0.1	0.35±0.05	1.5±0.1

Unit:mm

(3) Packaging Quantity

MCMB	0605
Chip / Reel	800

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 stadnard).

Tearing Speed mm	Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)
300±10%	5~35	45~85	860~1060

Soldering Specifications

(1) Soldering

Mildly activated rosin fluxes are preferred.metal-lions terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(2) Soldering Reflow:

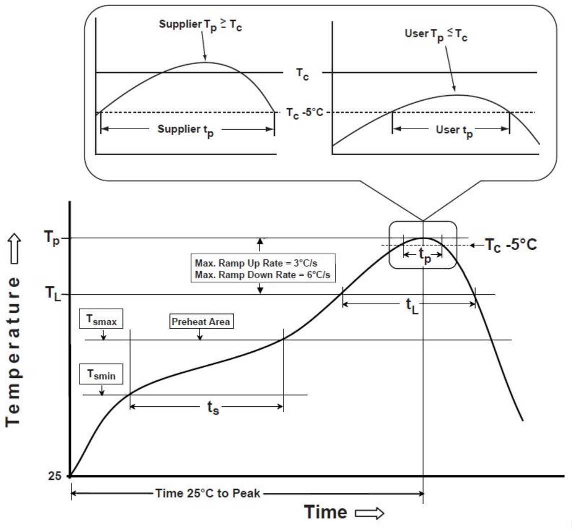
Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

(3) Iron Reflow:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.(Fig. 2)

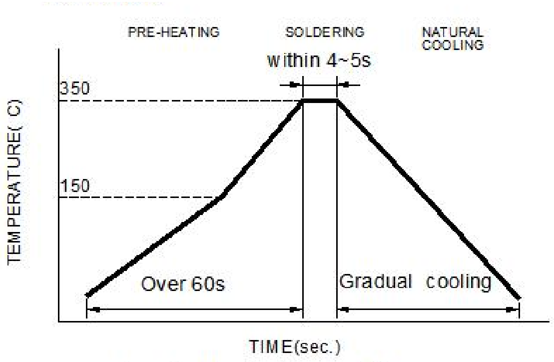
- Preheat circuit and products to 150℃
- 355℃ tip temperature (max)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times: 1 times max.

Soldering iron Method : 350± 5℃ max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	150℃ 200℃ 60-120seconds
Ramp-up rate($T_L$to T_p)	3℃/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217℃ 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at Tc- 5℃ (Tp should be equal to or less than Tc.)	*< 30 seconds
Ramp-down rate(T_p to T_L)	6℃ /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260℃	260℃	260℃
	1.6-2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

Reflow is referred to standard IPC/JEDEC J-STD-020E。

Notes

(1) When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition

(2) This power choke coil itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.

(3) When this power choke coil was used in a similar or new product to the original one, sometimes it might not be able to satisfy the specifications due to different condition of use.

(4) Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.

(5) This power choke coil must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low in this condition.

(6) Please consult our company to confirm the reliability of the process required to wash or use or exposure to a chemical solvent used in this product. PCB washing tested to MIL-STD-202 Method， and dry it off immediately。

(7) The rated current as listed is either the saturation current or the heating current depending on which value is lower.

(8) If this power choke is dipped in the cleaning agent, such as toluene, xylene, ketone, and ether system, there is a possibility that the performance decreases greatly， and marking disappearnc。

(9) The high power ultrasonic washing may damage the choke body。

(10) Before use， the user should determine whether this product is suitable for their own design， Our company only guarantees that the product meets the requirements of this specification。

Application Notice

- Storage Conditions
  To maintain the solderability of terminal electrodes:
  1. metal-lions products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 85% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.